



FOR IMMEDIATE RELEASE

Aehr Test Systems

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Aehr Test Systems Announces Delivery of New FOX-XP™ Wafer Level Test and Burn-in System

Fremont, CA (February 29, 2016) – Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced that it has received customer acceptance for and delivered its first FOX-XP Wafer Level Test and Burn-in System. The order included multiple FOX-XP WaferPak Contactors and application development services. The delivery occurred in the third quarter of Aehr Test's fiscal 2016, which closes on February 29, 2016.

Gayn Erickson, President and CEO of Aehr Test Systems, commented, "We are very excited to have delivered this first FOX-XP system and are pleased with the performance of this latest member of our FOX-P family. This system is configured for a single wafer but is scalable in our production systems for up to 25 wafers or more in parallel in a single test cell. In addition, this unique multi-wafer system uses our proprietary WaferPak wafer contactor, which is a critical portion of the solution for this particular application, due to certain specific technical requirements for testing and handling these wafers.

"This FOX-XP system and the WaferPak Contactors will be used for reliability and qualification test of sensor devices intended for a very high volume application. We believe our high power FOX-XP multi-wafer system is a perfect fit for this application and represents a significant new opportunity as this device moves into high volume manufacturing with wafer level burn-in. We believe the success of the engineering tests that are being run on this system will lead to volume production orders from this customer. This customer anticipates that they will need a significant number of systems to meet their device volume shipments beginning in the fourth quarter of this calendar year and ramp through the entire calendar years 2017 and 2018."

Aehr Test's FOX-XP system is the company's next-generation multi-wafer test solution that is capable of functional test and burn-in/cycling of flash memories, microcontrollers, sensors, and other leading-edge ICs in wafer form before they are assembled into single or multi-die stacked packages or for non-packaged die sales or applications where known good die is critical. These singulated die or single-die or stacked-die packaged parts can then be used for high reliability and quality applications such as enterprise solid state drives, automotive devices, highly valuable mobile applications, and mission critical integrated circuits and sensors. The FOX-XP system utilizes Aehr Test's FOX WaferPak contactor, which provides a cost effective solution for making electrical contact with a full wafer or substrate in a multi-wafer environment. Aehr Test's WaferPak contactors contain up to tens of thousands of probes to contact all devices on wafers and substrates up to 300mm simultaneously. The FOX-XP system is being developed in configurations of 25 wafers in parallel in a single cell to operate within an efficient manufacturing space footprint. Aehr Test estimates the test equipment and consumables for the emerging multi-wafer level test and burn-in market will add \$200 million to \$300 million to its served available market.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX families of test and burn-in systems and the DiePak® carrier. The ABTS system is used in production and qualification testing of packaged parts for both lower-power and higher-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company's website at www.aehr.com.

Safe Harbor Statement

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. Forward-looking statements include statements regarding Aehr Test's expectations, beliefs, intentions or strategies regarding the FOX products, including statements regarding future market opportunities and conditions, expected product shipment dates and customer orders or commitments. These risks and uncertainties include, without limitation, acceptance by customers of the FOX and WaferPak contactor technologies, acceptance by customers of the FOX-XP system, WaferPak Aligner and WaferPak contactors shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described, as well as general market conditions, customer demand and acceptance of Aehr Test's products and Aehr Test's ability to execute on its business strategy. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing Aehr Test's business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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